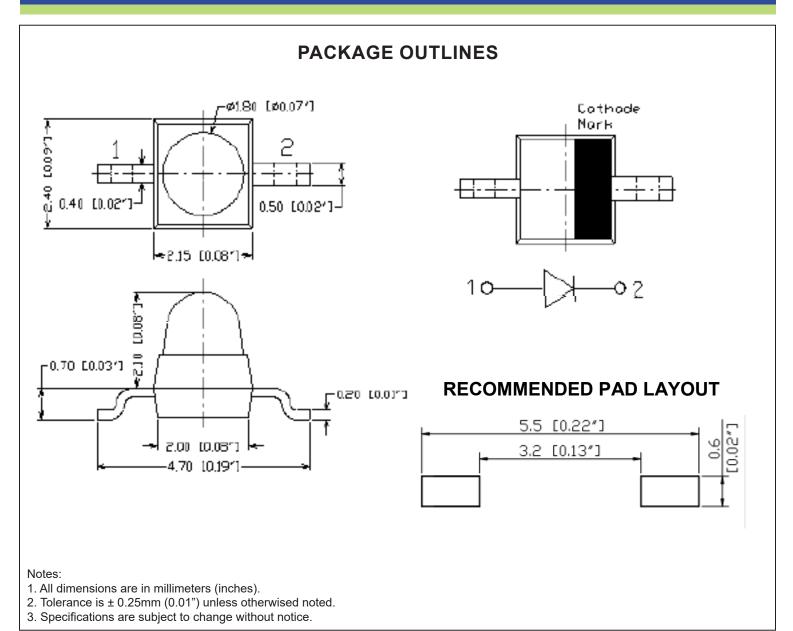


SPECIFICATION CSM28GT2CG



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle	
CSM28GT2CG	InGaN	Green	Water Clear	20°	





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	111	mW	
Operating Temperature Range	Тор	-40~+80	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	125	mA	
Soldering Temperature	TsoL	Max 260°C for 5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Parameter	Symbol	Toot Condition	Value			Llmit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	4000	8000	-	mcd
Forward Voltage	VF	IF = 20mA	1	3.1	3.7	V
Reverse Leakage Current	lR	VR = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 10mA	1	20	-	Deg
Peak Wavelength	λР	IF = 20mA	-	520	-	nm
Dominant Wavelength	λD	IF = 20mA	520	525	530	nm

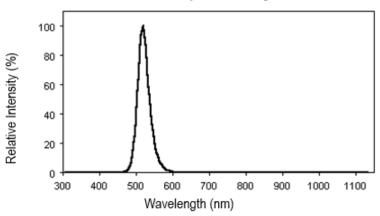
^{*}Tolerance of viewing angle: -10 / +5 deg.



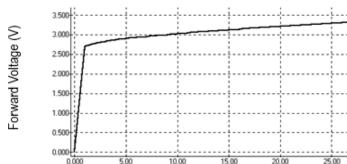


OPTICAL CHARACTERISTIC CURVES

Relative Intensity vs. Wavelength

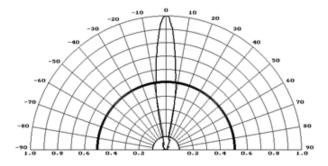


Forward Current vs. Forward Voltage



Forward Current (mA)

Directive Characteristics

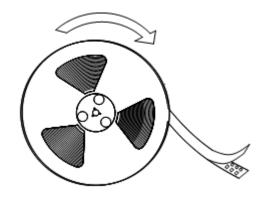




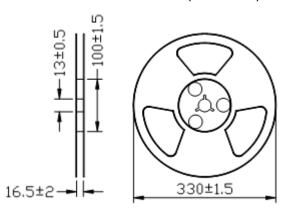


PACKAGING SPECIFICATION

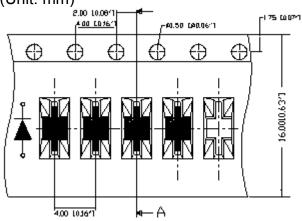
Feeding Direction

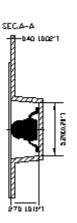


Dimensions of Reel (Unit: mm)

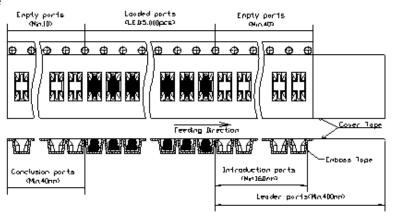


Dimensions of Tape (Unit: mm)





Arrangement of Tape



Notes:

- 1. Empty component pockets are sealed with top cover tape
- 2. Maximum number of missing lamp is two
- 3. Cathode is oriented towards the tape sprocket hole
- 4. 1,500(Max) pcs/Reel

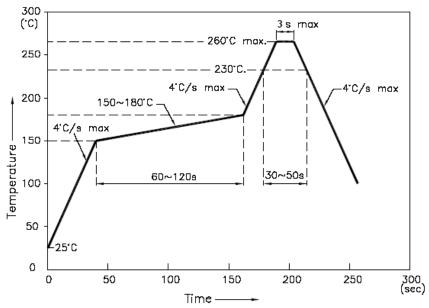




SOLDERING CONDITIONS

REFLOW PROFILE

Reflow Temp/Time



Notes:

- 1. We recommend the reflow temperature 245°C (± 5 °C). The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process should be 2 times or less.

Soldering Iron

Basic spec is ≤ 5 sec when 260°C. If temperature is higher, time should be shorter ($\pm 10^{\circ}\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of the device should be under 230°C.